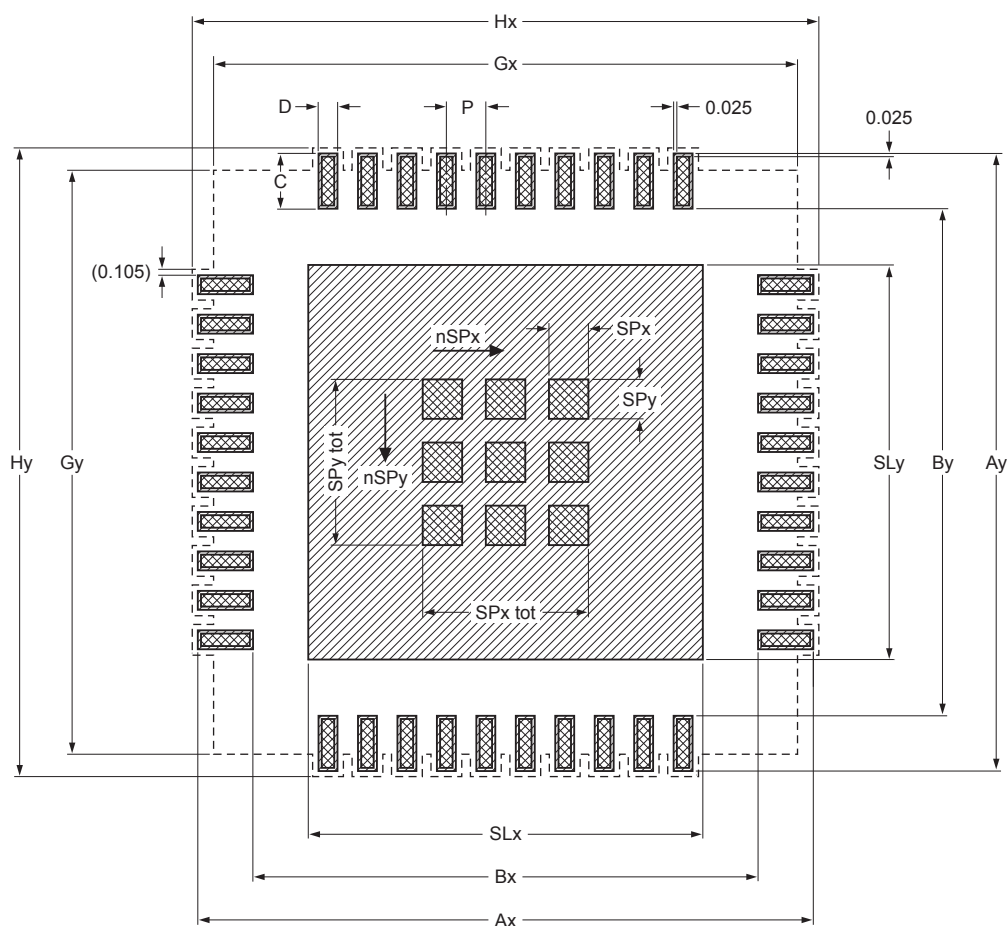**Footprint information for reflow soldering of HVQFN40 package**   **SOT618-1**

Generic footprint pattern
Refer to the package outline drawing for actual layout

	occupied area		solder resist
	solder lands		solder paste

nSPx	nSPy
3	3

Dimensions in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	7.000	7.000	5.200	5.200	0.900	0.290	4.100	4.100	2.400	2.400	0.600	0.600	6.300	6.300	7.250	7.250

Issue date	~~09-06-11~~ 14-08-13	*sot618-1_fr*